

Automotive MOSFET

OptiMOS™ 7 Power-Transistor







Features

- OptiMOS[™] power MOSFET for automotive applications
- N-channel Enhancement mode Normal Level
- Extended qualification beyond AEC-Q101
- Enhanced electrical testing
- Robust design
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- · RoHS compliant
- 100% Avalanche tested



General automotive applications.



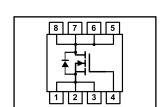
Qualified for automotive applications. Product validation according to AEC-Q101.

Product Summary

V_{DS}	100	V
R _{DS(on)}	2.1	mΩ
I _D (chip limited)	220	Α

Туре	Package	Marking
IAUCN10S7N021	PG-TDSON-8-53	7N10N021





IAUCN10S7N021



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Maximum Ratings

at $T_j = 25$ °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I _D	$V_{GS} = 10 \text{ V}$, Chip limitation ^{1,2)}	220	А
		$V_{\rm GS}$ = 10 V, DC current	175	
		$T_a = 100^{\circ}\text{C}, V_{GS} = 10 \text{ V}, R_{thJA}$ on 2s2p ^{2,3)}	25	
Pulsed drain current ²⁾	I _{D,pulse}	$T_{\rm C}$ = 25°C, $t_{\rm p}$ = 100 μ s	779	
Avalanche energy, single pulse ²⁾	E _{AS}	I _D = 65 A	288	mJ
Avalanche current, single pulse	I _{AS}	-	130	Α
Gate source voltage	V_{GS}	-	±20	V
Power dissipation	P_{tot}	T _C = 25°C	217	W
Operating and storage temperature	$T_{\rm j}, T_{\rm stg}$	-	-55 +1 75	°C

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Thermal Characteristics²⁾

Davamatav	Symbol	Symbol Conditions	Values			I I mit
Parameter	Symbol	Conditions	min.	typ.	max.	Unit
Thermal resistance, junction - case	R _{thJC}	-	_	_	0.69	K/W
Thermal resistance, junction - ambient ³⁾	R_{thJA}	-	-	25.9	-	

Electrical Characteristics

at T_i=25 °C, unless otherwise specified

Parameter	Sumah al	Symbol Conditions	Values				
	Symbol		min.	typ.	max.	Unit	
Static Characteristics							
Drain-source breakdown voltage	V _{(Br)DSS}	$V_{GS} = 0 \text{ V},$ $I_D = 1 \text{ mA}$	100	-	-	V	
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 130 \mu\text{A}$	2.3	2.8	3.2		
		$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_j = 25^{\circ}\text{C}$	-	_	1	μА	
Zero gate voltage drain current	/ _{DSS}	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V},$ $T_j = 100^{\circ}\text{C}^{2j}$	-	_	32		
Gate-source leakage current	I _{GSS}	$V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	100	nA	
Drain-source on-state resistance		$V_{GS} = 7 \text{ V}, I_D = 44 \text{ A}$	-	2.0	2.4	mΩ	
	R _{DS(on)}	$V_{\rm GS} = 10 \text{V}, I_{\rm D} = 88 \text{A}$	-	1.8	2.1		
Gate resistance ²⁾	R _G	-	-	2.2	-	Ω	





Parameter	Symbol Conditions	Values			11:4:4		
	Symbol	1 - 2	min.	typ.	max.	Unit	
Dynamic Characteristics ²⁾							
Input capacitance	Ciss		_	5502	7153	pF	
Output capacitance	C oss	$V_{GS} = 0 \text{ V}, V_{DS} = 50 \text{ V}, f = 1 \text{ MHz}$	_	2292	2980		
Reverse transfer capacitance	C _{rss}		-	21	32		
Turn-on delay time	t _{d(on)}		-	10	-	ns	
Rise time	t _r	$V_{DD} = 50 \text{ V}, V_{GS} = 10 \text{ V},$ $I_{D} = 88 \text{ A}, R_{G} = 3.5 \Omega$	_	10	-		
Turn-off delay time	t _{d(off)}		_	16	-		
Fall time	t _f		_	11	_		

Gate Charge Characteristics2)

Gate to source charge	Q _{gs}		-	27	35	nC
Gate to drain charge	Q _{gd}	$V_{DD} = 50 \text{ V}, I_D = 88 \text{ A},$	_	18	27	
Gate charge total	Qg	$V_{DD} = 50 \text{ V}, I_{D} = 88 \text{ A},$ $V_{GS} = 0 \text{ to } 10 \text{ V}$	-	81	105	
Gate plateau voltage	V _{plateau}		-	4.6	-	V

Reverse Diode

Diode continuous forward current ²⁾	Is	T _C = 25°C	ı	ı	175	А
Diode pulse current ²⁾	I _{S,pulse}	$T_{\rm C} = 25^{\circ}{\rm C}, t_{\rm p} = 100 \mu{\rm s}$	ı	ı	779	
Diode forward voltage	V _{SD}	$V_{GS} = 0 \text{ V}, I_F = 88 \text{ A}, T_j = 25^{\circ}\text{C}$	ı	0.9	1.0	V
Reverse recovery time ²⁾	t _{rr}	V _R = 50 V, I _F = 50 A	-	45	68	ns
Reverse recovery charge ²⁾	Q _{rr}	$di_F/dt = 100 A/\mu s$	_	41	83	nC

 $^{^{1)}}$ Practically the current is limited by the overall system design including the customer-specific PCB.

 $^{^{2)}}$ The parameter is not subject to production testing – specified by design.

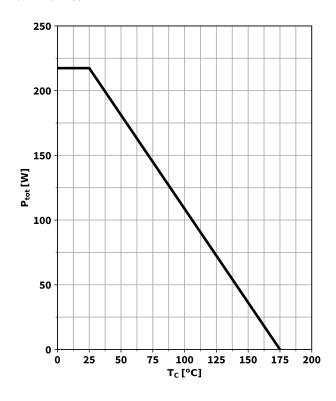
³⁾ Device on 2s2p FR4 PCB defined in accordance with JEDEC standards (JESD51-5, -7). PCB is vertical in still air.



Electrical characteristics diagrams

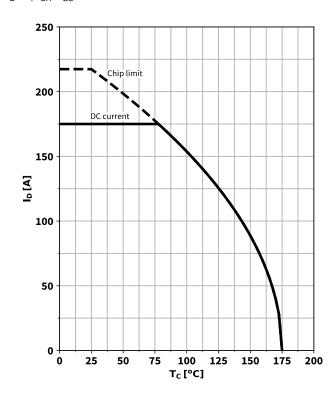
1 Power dissipation

 $P_{\text{tot}} = f(T_{\text{C}}); V_{\text{GS}} \ge 6 \text{ V}$



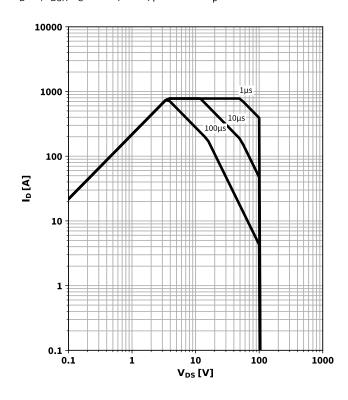
2 Drain current

 $I_{D} = f(T_{C}); V_{GS} \ge 6 \text{ V}$



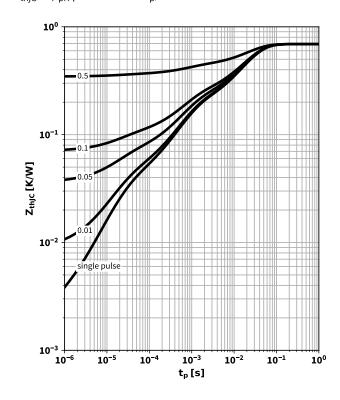
3 Safe operating area

 $I_{\rm D}$ = f($V_{\rm DS}$); $T_{\rm C}$ = 25 °C; D = 0; parameter: $t_{\rm p}$



4 Max. transient thermal impedance

 $Z_{\text{thJC}} = f(t_p)$; parameter: D = t_p/T

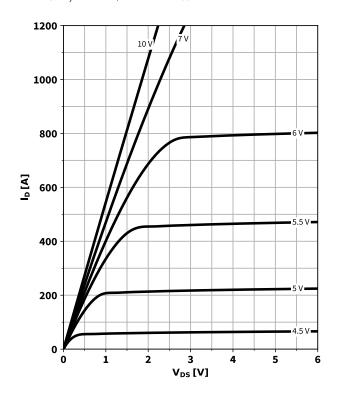


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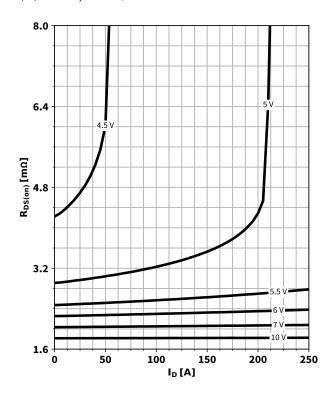
5 Typ. output characteristics

 $I_D = f(V_{DS}); T_j = 25$ °C; parameter: V_{GS}



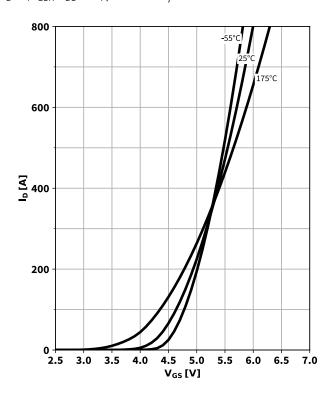
6 Typ. drain-source on-state resistance

 $R_{DS(on)} = f(I_D); T_j = 25 \text{ °C}; parameter: } V_{GS}$



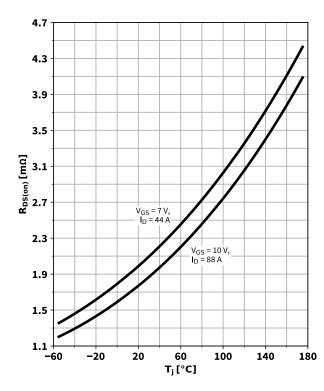
7 Typ. transfer characteristics

 $I_D = f(V_{GS}); V_{DS} = 6 \text{ V}; \text{ parameter: } T_j$



8 Typ. drain-source on-state resistance

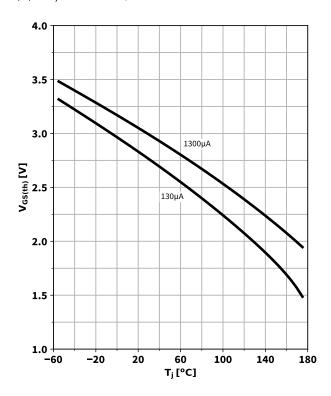
 $R_{DS(on)} = f(T_j)$; parameter: I_D , V_{GS}





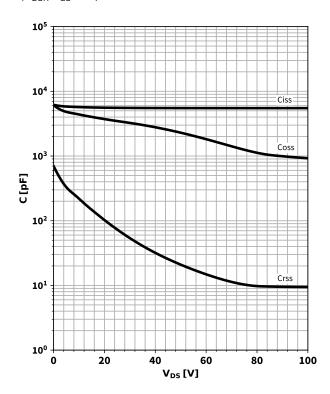
9 Typ. gate threshold voltage

 $V_{\text{GS(th)}} = f(T_{\text{j}}); V_{\text{GS}} = V_{\text{DS}}; \text{ parameter: } I_{\text{D}}$



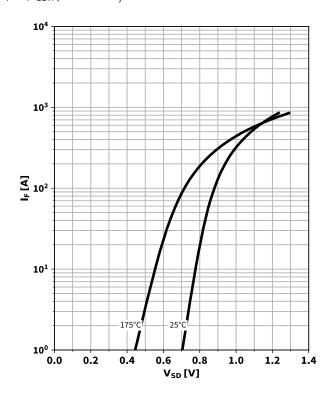
10 Typ. capacitances

 $C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$



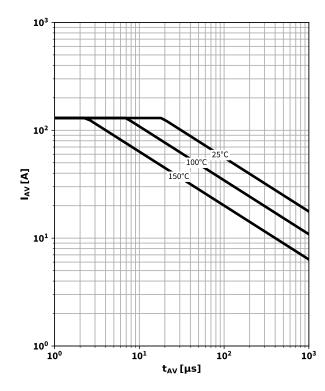
11 Typ. forward diode characteristics

 $I_F = f(V_{SD})$; parameter: T_j



12 Typ. avalanche characteristics

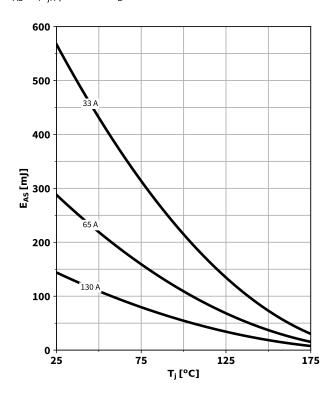
 $I_{AS} = f(t_{AV})$; parameter: $T_{j(start)}$





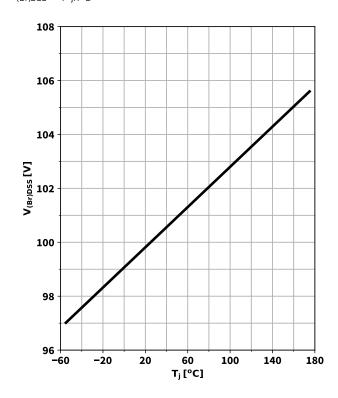
13 Typical avalanche energy

 $E_{AS} = f(T_j)$; parameter: I_D



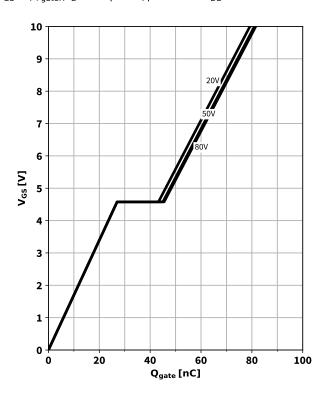
14 Drain-source breakdown voltage

$$V_{(Br)DSS} = f(T_j); I_D = 1 \text{ mA}$$

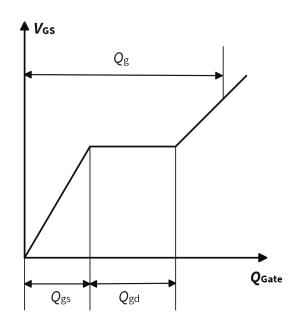


15 Typ. gate charge

 $V_{GS} = f(Q_{gate}); I_D = 88 \text{ A pulsed}; parameter: } V_{DD}$



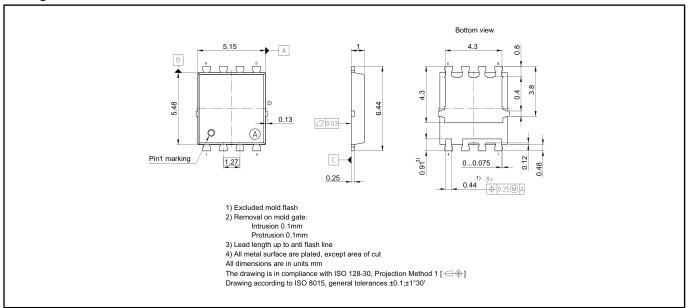
16 Gate charge waveforms



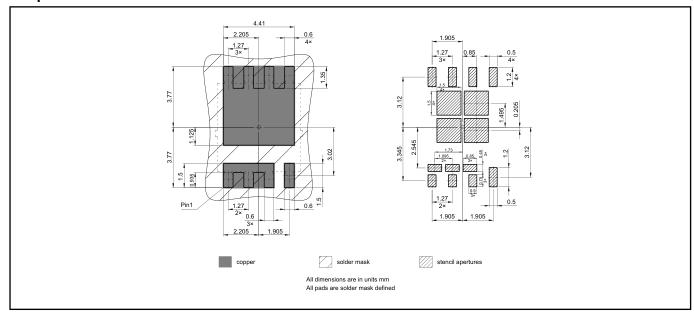
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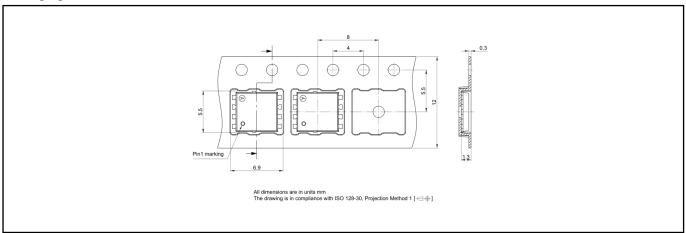
Package Outline



Footprint



Packaging



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Revision History

Revision	Date Changes			
Revision 1.0	2024-03-07	final data sheet		
Revision 1.1	2024-04-15	package name (page 1)		

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